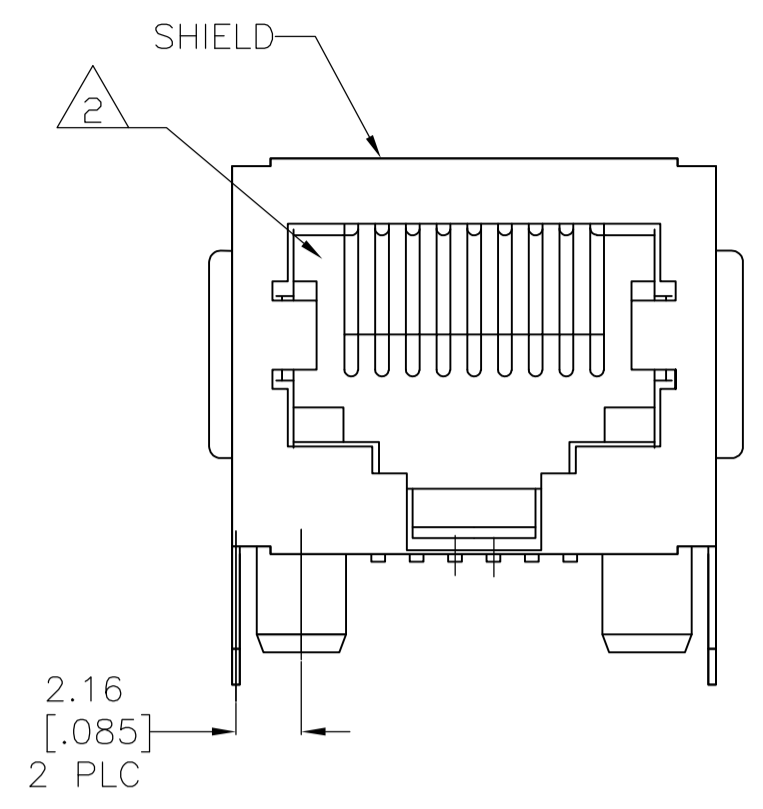
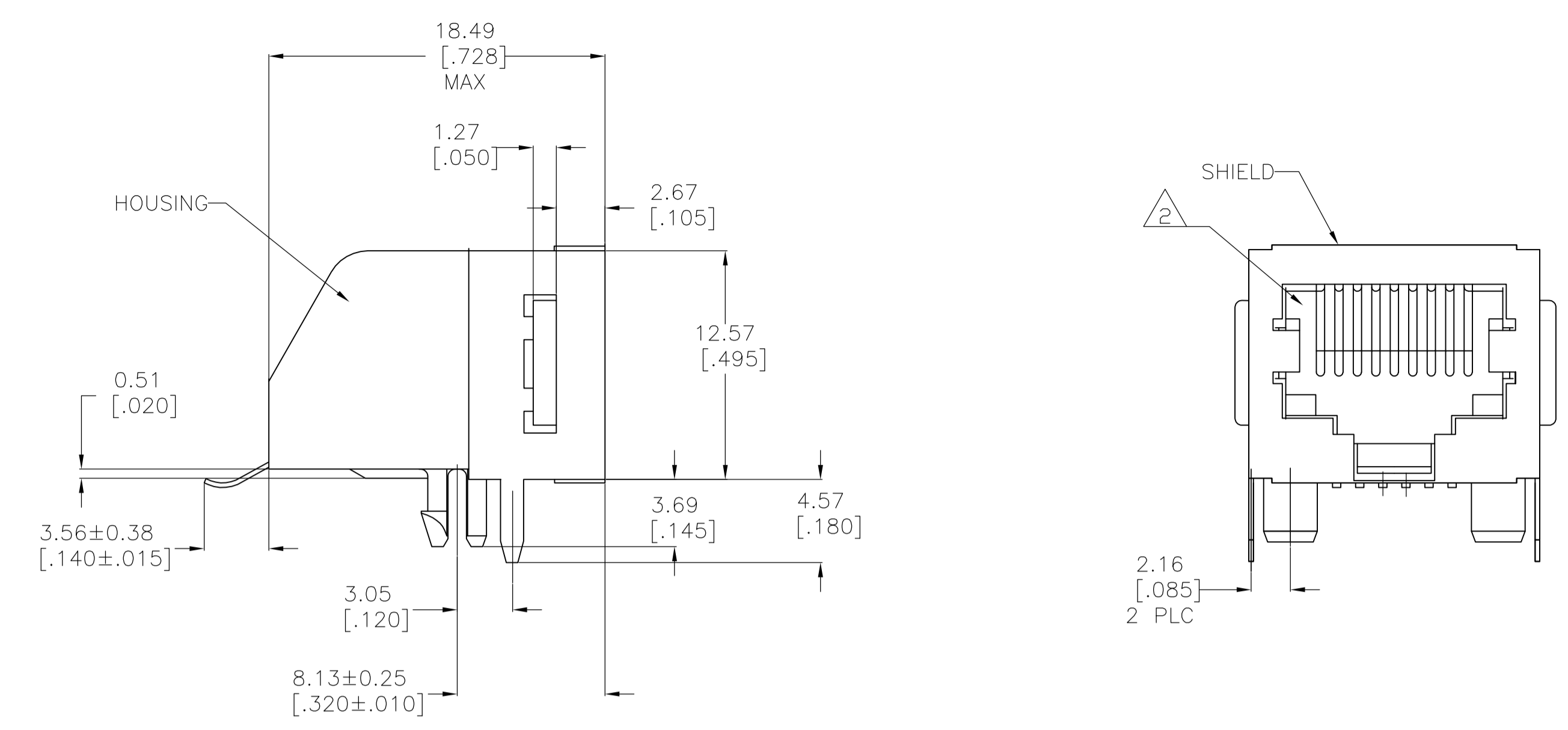
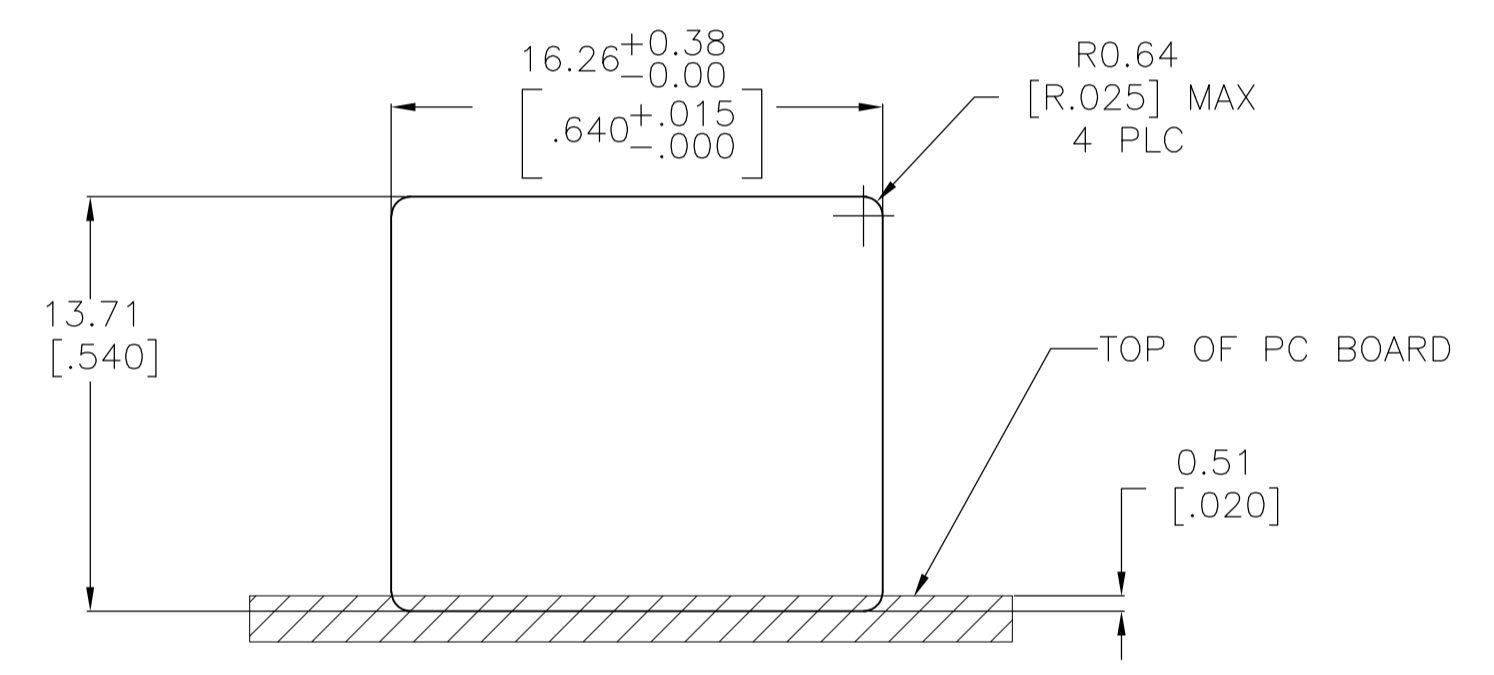
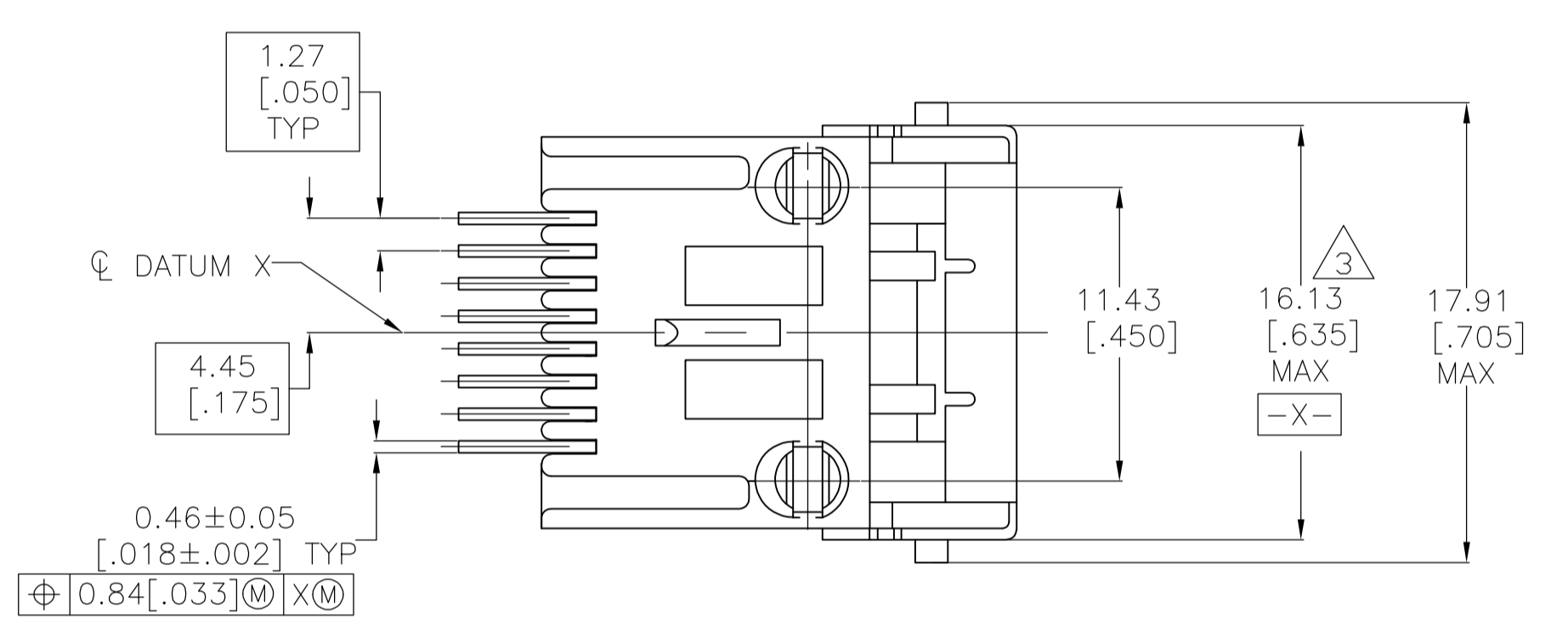


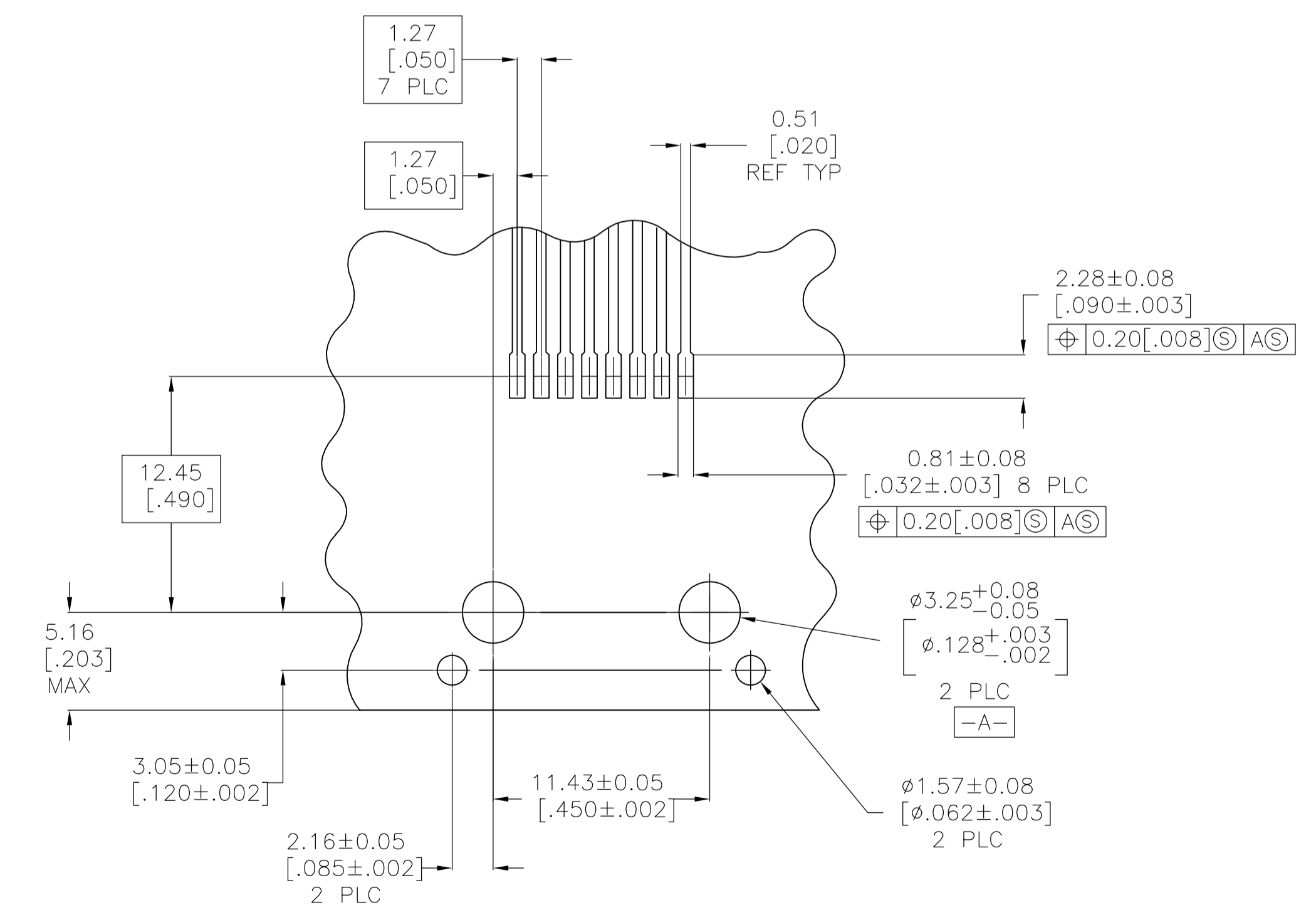
LOC		DIST		REVISIONS			
P	LTR	DESCRIPTION	DATE	DMN	APVD		
D1		REVISED PER ECO-11-005140	28MAR11	RK	HMR		



- MATERIAL:
HOUSING - HTN NYLON MOLDING COMPOUND, 94 VO, COLOR: BLACK
TERMINAL - 0.36[.014] THICK PHOS-BRONZE
PLATED WITH 1.27 μ m[.000050] MINIMUM THICK HARD GOLD IN LOCALIZED GOLD PLATE AREA AND 3.81 μ m[.000150] MINIMUM THICK MATTE TIN IN SOLDER AREA OVER 1.27 μ m[.000050] THICK MINIMUM NICKEL UNDERPLATE.
SHIELD - 0.25[.010] THICK COPPER ALLOY PLATED WITH 3.0 μ m[.000120] MINIMUM REFLOWED TIN
- CAVITY CONFORMS TO FCC RULES AND REGULATIONS, PART 68, SUBPART F
- DIMENSION MEASURED ALONG FRONT EDGES OF MATING FACE
- PACKAGING TAPE AND REEL: (PER EIA 481 SPECIFICATION)
TAPE: 44[1.73] WIDE
POCKET DEPTH: 17.65[.695]
POCKET PITCH: 32[1.26]
CLEAR PSA TAPE TRAILER 160[6.30] MIN LENGTH
PLASTIC REEL DIA 330[13.0]
PIECES PER REEL: 100
- SNAP-IN RETENTION FEATURE ACCOMMODATES 1.44-1.71 [.062±.005] THICK PRINTED CIRCUIT BOARD.



RECOMMENDED PANEL CUTOUT



RECOMMENDED PRINTED CIRCUIT BOARD LAYOUT (COMPONENT SIDE)

SUPERSEDED BY -1	TAPE & REEL	5558178-2
	TRAY	5558178-1
	PACKAGING TYPE	PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT.		DIN R.GRZYBOWSKI		08NOV2004		STE TE Connectivity	
DIMENSIONS: mm [INCHES]		CHK J.WESTMAN		08NOV2004		NAME	
TOLERANCES UNLESS OTHERWISE SPECIFIED:		APVD S.FLICKINGER		08NOV2004		PRODUCT SPEC	
0 PLC ± -						MODULAR JACK ASSEMBLY, 8 POSITION, RIGHT ANGLE, SURFACE MOUNTING, SHIELDED, LOW PROFILE, PRINTED	
1 PLC ± -						APPLICATION SPEC	
2 PLC ± 0.13[.005]						108-1163	
3 PLC ± -						SIZE	
4 PLC ± -						114-6040	
ANGLES ± 1°						SCALE	
MATERIAL SEE NOTE 1		FINISH SEE NOTE 1		WEIGHT -		A1 00779 5558178	
						CUSTOMER DRAWING	
						SHEET 1 OF 1	
						REV D1	

单击下面可查看定价，库存，交付和生命周期等信息

[>>TE Connectivity\(泰科\)](#)